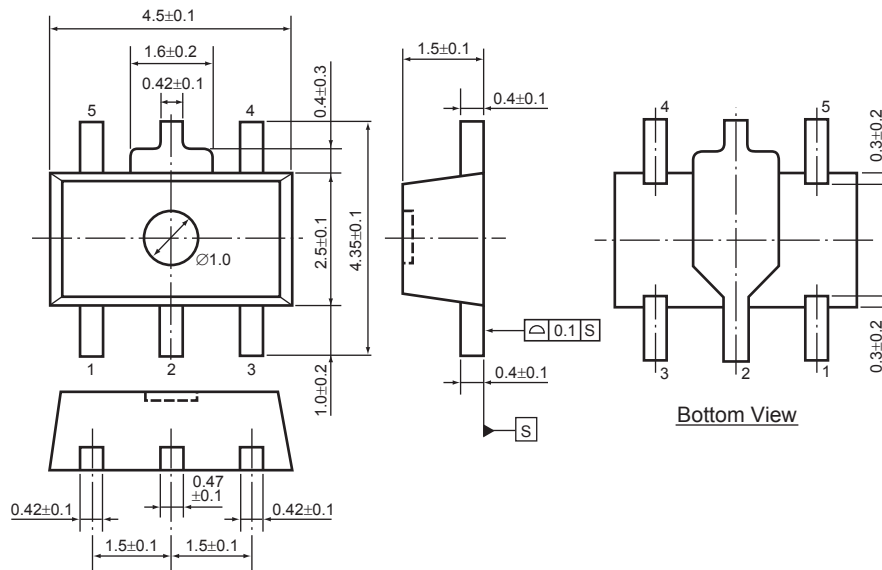


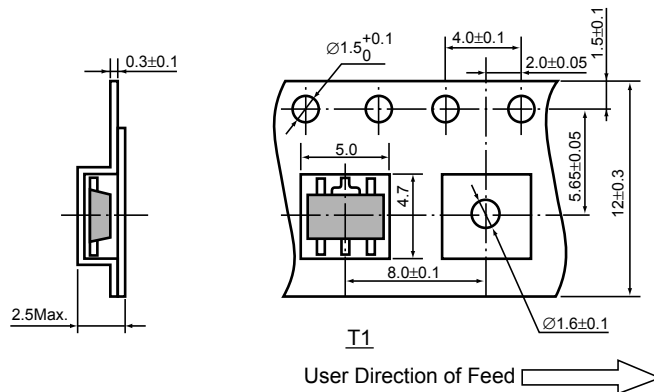
• SOT-89-5

Unit: mm

PACKAGE DIMENSIONS

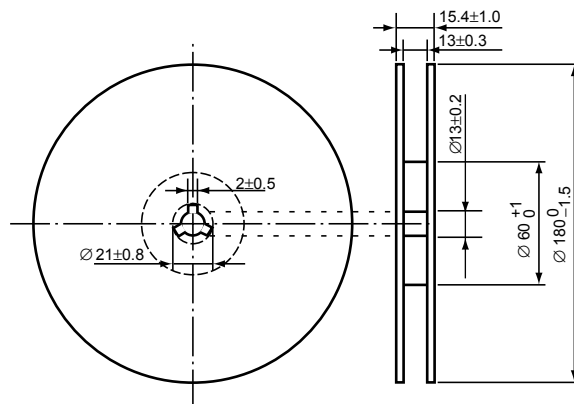


TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-12Bc)

1 reel = 1,000 pcs



POWER DISSIPATION (SOT-89-5)

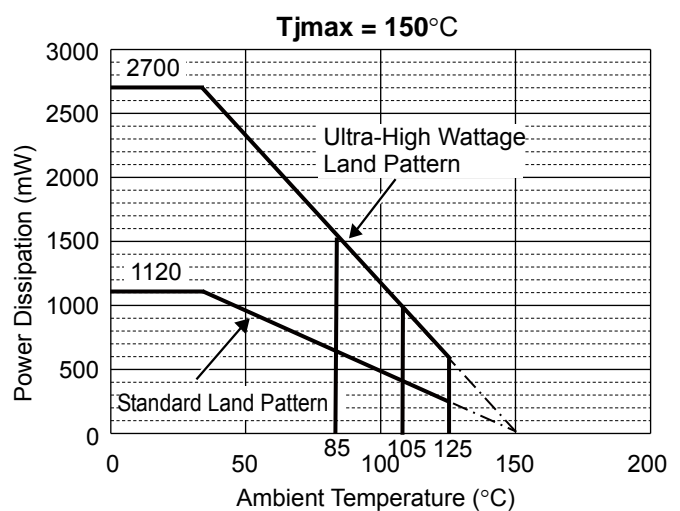
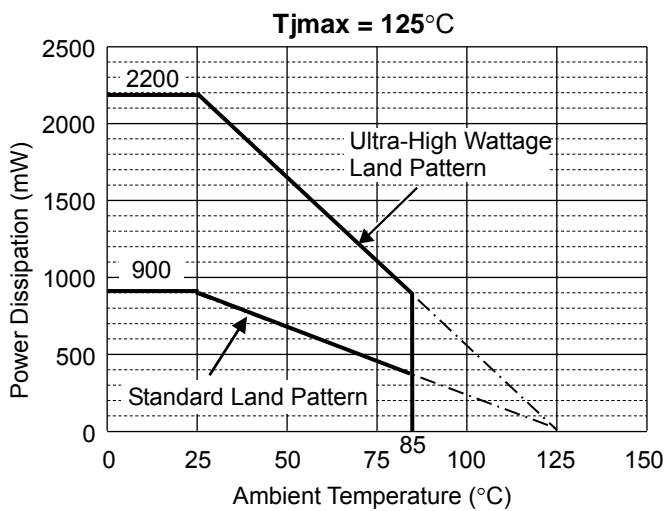
Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

Measurement Conditions

	Standard Test Land Pattern	Ultra-High Wattage Test Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)	Glass cloth epoxy plastic (Four-layers)
Board Dimensions	40 mm x 40 mm x 1.6 mm	76.2 mm x 114.3 mm x 0.8 mm
Copper Ratio	Top side: Approx. 10%, Back side: Approx. 100%	Top side, Back side : 50 mm×50 mm, Approx.96% 2nd, 3rd Layer : 50 mm×50 mm, Approx. 100%
Through-holes	—	φ 0.3mm x 28pcs.

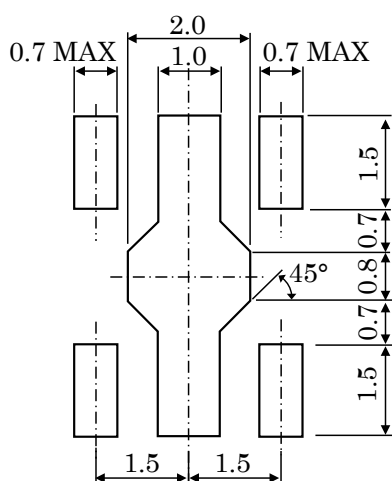
Measurement Result ($T_a=25^\circ\text{C}$)

	Standard Test Land Pattern	Ultra-High Wattage Test Land Pattern
Power Dissipation	900 mW ($T_{jmax} = 125^\circ\text{C}$) 1120 mW ($T_{jmax} = 150^\circ\text{C}$)	2200 mW ($T_{jmax} = 125^\circ\text{C}$) 2700 mW ($T_{jmax} = 150^\circ\text{C}$)
Thermal Resistance	$\theta_{ja} = 111^\circ\text{C/W}$	$\theta_{ja} = 46^\circ\text{C/W}$ $\theta_{jc} = 16^\circ\text{C/W}$

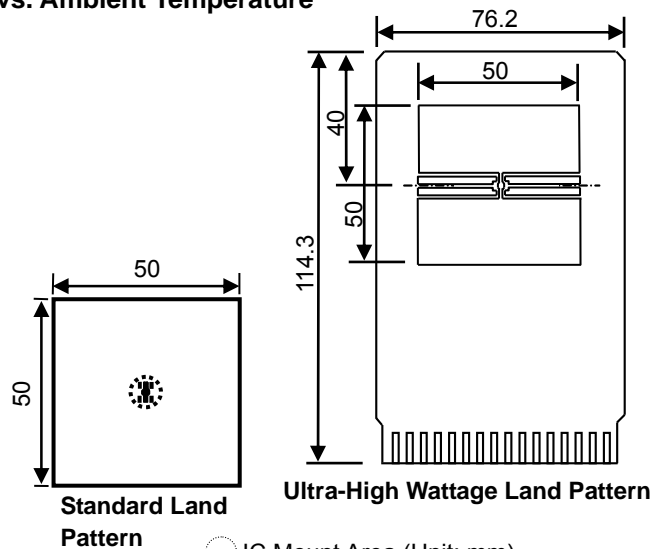


Power Dissipation vs. Ambient Temperature

RECOMMENDED LAND PATTERN



(Unit: mm)



○ IC Mount Area (Unit: mm)
Measurement Board Pattern